



Description:

Powerex Dual Mosfet Module designed specially for customer applications.

Features:

- Isolated Mounting
- Copper Baseplate
- Low Drive Requirement
- Internal Series Gate Resistors (6Ω per chip)
- Low Rds(on)
- Fast Diodes
- (6) FS70UMJ-2 Chips per Mosfet Switch

Dim	Inches	Millimeters
A	3.70	94.0
B	3.150 ±0.01	80.0 ±0.25
C	1.89	48.0
D	1.18 Max.	30.0 Max
E	0.90	23.0
F	.83	21.2
G	0.71	18.0
H	0.67	17.0
J	0.63	16.0
K	0.51	13.0
L	0.47	12.0
M	0.30	7.5
N	0.28	7.0
P	0.256 Dia.	Dia. 6.5
Q	0.26	6.5
R	---	M5
S	0.16	4.0

Electrical Characteristics ($T_C = 25^\circ\text{C}$)

Symbol	Parameter	Min.	Typ.	Max.	Units
$V_{(BR)DSS}$	Drain Source Breakdown Voltage $I_D=6\text{mA}$, $V_{GS}=0$	100	--	--	V
V_{GSS}	Gate Source Voltage $V_{DS}=0$	--	--	± 20	V
I_{GSS}	Gate Leakage Current $V_{GS}=\pm 20\text{V}$, $V_{DS}=0$	--	--	± 0.6	μA
I_{DSS}	Drain Leakage Current $V_{DS}=100\text{V}$, $V_{GS}=0$	--	--	0.6	mA
$V_{GS(th)}$	Gate Source Threshold Voltage $I_D=6\text{mA}$, $V_{DS}=10\text{V}$	1.0	1.5	2.0	V
$R_{DS(ON)}$	Drain Source On State Resistance $I_D=210\text{A}$, $V_{GS}=10\text{V}$	--	2.2	2.8	m Ω
$V_{DS(ON)}$	Drain Source On-State Voltage $I_D=210\text{A}$, $V_{GS}=10\text{V}$	--	0.46	0.6	V
C_{iss}	Input Capacitance $V_{DS}=10\text{V}$, $V_{GS}=0$, $f = 1\text{MHz}$	--	49200	--	pF
C_{oss}	Output Capacitance $V_{DS}=10\text{V}$, $V_{GS}=0$, $f = 1\text{MHz}$	--	6900	--	pF
C_{rss}	Reverse Transfer Capacitance $V_{DS}=10\text{V}$, $V_{GS}=0$, $f = 1\text{MHz}$	--	3600	--	pF
V_{SD}	Source Drain Voltage $I_S=210\text{A}$, $V_{GS}=0\text{V}$	--	1.0	1.5	V
$R_{th(j-c)}$	Thermal Impedance Junction to Case (Per MOSFET)	--	0.13	0.16	$^\circ\text{C/W}$
T_J	Junction Temperature	-40	--	125	$^\circ\text{C}$
PACKAGE					
V_{rms}	V Isolation	--	--	2000	VAC
	Module weight	--	270	--	g
	Mounting torque M5 Terminal Screw	--	--	4	Nm
	Terminal torque, M6 Mounting Screw	--	--	6	Nm
$R_{th(c-s)}$	Thermal Impedance Case to Sink	--	--	0.035	$^\circ\text{C/W}$